## nexperia

## **Quarterly Reliability Monitoring Results**

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier		User Part Number						
Nexperia B.V.		PMEG3001EEF						
Name of Laboratory Assembly reliability labs Test		Part Description						
		Nexperia DHAM	Schottky					
		BD						
		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
	TEST Pre- and Post-Stress							
# 1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
		MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet						
# 5	Bias	reverse voltage <sup>[1]</sup>	1000 hours	36	2880	0		
# 7	<b>TC</b> Temperature Cycling	JESD22-A104 -40 °C to 125°C	1000 cycles	36	2880	0		
# 8	<b>AC</b> Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	n.a.	n.a.	n.a.		
# 9	<b>H3TRB</b> High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage <sup>[1], [2]</sup>	1000 hours	n.a.	n.a.	n.a.		
# 10	<b>IOL</b> Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure $\Delta Tj$ = 100 °C for 15000 cycles	1000 hours	36	2880	0		
	RSH	JESD22-A111						
# 20	Resistance to Solder Heat	260 °C ± 5 °C	10 s	n.a.	n.a.	n.a.		
# 21	<b>SD</b> Solderability	J-STD-002		36	360	0		

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	2880	0	1.47	6.78E+08

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